Zj Pei

List of Publications by Year
in descending order

72 papers	3,663 citations	109321 35 h-index	133252 59 g-index
73 all docs	73 docs citations	73 times ranked	1289 citing authors

#	Article	IF	Citations
1	A feeding-directional cutting force model for end surface grinding of CFRP composites using rotary ultrasonic machining with elliptical ultrasonic vibration. International Journal of Machine Tools and Manufacture, 2020, 152, 103540.	13.4	66
2	A mechanistic cutting force model based on ductile and brittle fracture material removal modes for edge surface grinding of CFRP composites using rotary ultrasonic machining. International Journal of Mechanical Sciences, 2020, 176, 105551.	6.7	51
3	Fixed abrasive machining of non-metallic materials. CIRP Annals - Manufacturing Technology, 2018, 67, 767-790.	3.6	30
4	Surface grinding of carbon fiberâ€"reinforced plastic composites using rotary ultrasonic machining: Effects of tool variables. Advances in Mechanical Engineering, 2016, 8, 168781401667028.	1.6	28
5	Experimental investigations on core drilling by ultrasonic-vibration-assisted grinding for hard-to-machine materials - a review. International Journal of Manufacturing Research, 2016, 11, 28.	0.2	3
6	Rotary ultrasonic machining of CFRP: A comparison with grinding. Ultrasonics, 2016, 66, 125-132.	3.9	131
7	Ultrasonic vibration-assisted (UV-A) pelleting of wheat straw: A constitutive model for pellet density. Ultrasonics, 2015, 60, 117-125.	3.9	8
8	Effects of ultrasonic vibration-assisted pelleting on chemical composition and sugar yield of corn stover and sorghum stalk. Renewable Energy, 2015, 76, 160-166.	8.9	20
9	Preliminary study on rotary ultrasonic machining of CFRP/Ti stacks. Ultrasonics, 2014, 54, 1594-1602.	3.9	68
10	Ultrasonic vibration-assisted pelleting of wheat straw: A predictive model for energy consumption using response surface methodology. Ultrasonics, 2014, 54, 305-311.	3.9	25
11	Rotary ultrasonic machining of CFRP: A mechanistic predictive model for cutting force. Ultrasonics, 2014, 54, 663-675.	3.9	125
12	Rotary ultrasonic machining of CFRP/Ti stacks using variable feedrate. Composites Part B: Engineering, 2013, 52, 303-310.	12.0	64
13	Energy consumption study in ultrasonic vibration-assisted pelleting of wheat straw for cellulosic biofuel manufacturing. International Journal of Manufacturing Research, 2013, 8, 135.	0.2	7
14	Surface roughness in rotary ultrasonic machining: hypotheses and their testing via experiments and simulations. International Journal of Manufacturing Research, 2013, 8, 378.	0.2	5
15	Cutting temperature in rotary ultrasonic machining of titanium: experimental study using novel Fabry-Perot fibre optic sensors. International Journal of Manufacturing Research, 2013, 8, 250.	0.2	17
16	Rotary ultrasonic machining of carbon fiber-reinforced plastic composites: using cutting fluid vs. cold air as coolant. Journal of Composite Materials, 2012, 46, 1745-1753.	2.4	69
17	Preliminary study on pretreatment of poplar wood for biofuel production. Biofuels, 2012, 3, 525-533.	2.4	3
18	Ultrasonic vibration-assisted pelleting of wheat straw: a predictive model for pellet density using response surface methodology. Biofuels, 2012, 3, 259-267.	2.4	7

#	ARTICLE	IF	CITATIONS
19	Rotary ultrasonic machining of carbon fiber reinforced plastic composites: An experimental study on cutting temperature. Journal of Reinforced Plastics and Composites, 2012, 31, 1516-1525.	3.1	38
20	Ultrasonic-vibration-assisted pelleting of wheat straw: an experimental investigation. International Journal of Manufacturing Research, 2012, 7, 59.	0.2	9
21	Edge chipping in rotary ultrasonic machining of silicon. International Journal of Manufacturing Research, 2012, 7, 311.	0.2	22
22	Effects of pellet weight in ultrasonic vibration-assisted pelleting for cellulosic biofuel manufacturing. International Journal of Manufacturing Research, 2012, 7, 397.	0.2	5
23	Rotary ultrasonic machining of CFRP composites: A study on power consumption. Ultrasonics, 2012, 52, 1030-1037.	3.9	57
24	Rotary ultrasonic machining of CFRP: A comparison with twist drilling. Journal of Reinforced Plastics and Composites, 2012, 31, 313-321.	3.1	69
25	Ultrasonic vibration-assisted (UV-A) machining of composites. , 2012, , 185-201.		0
26	A cutting force model for rotary ultrasonic machining of brittle materials. International Journal of Machine Tools and Manufacture, 2012, 52, 77-84.	13.4	178
27	Non-traditional drilling of SiC based ceramic matrix composites: a literature review. International Journal of Machining and Machinability of Materials, 2011, 10, 235.	0.1	6
28	An experimental study on charring of cellulosic biomass in ultrasonic vibration-assisted pelleting. International Journal of Manufacturing Research, 2011, 6, 77.	0.2	13
29	Physical properties of pellets made from sorghum stalk, corn stover, wheat straw, and big bluestem. Industrial Crops and Products, 2011, 33, 325-332.	5.2	170
30	Rotary Ultrasonic Machining of stainless steels: empirical study of machining variables. International Journal of Manufacturing Research, 2010, 5, 370.	0.2	20
31	Ice Cream: Foam Formation and Stabilizationâ€"A Review. Food Reviews International, 2010, 26, 122-137.	8.4	27
32	Rotary ultrasonic machining of potassium dihydrogen phosphate (KDP) crystal: An experimental investigation on surface roughness. Journal of Manufacturing Processes, 2009, 11, 66-73.	5.9	66
33	Wheel wear mechanisms for silicon grinding: a literature review. International Journal of Machining and Machinability of Materials, 2009, 5, 60.	0.1	1
34	Rotary ultrasonic machining of dental ceramics. International Journal of Machining and Machinability of Materials, 2009, 6, 270.	0.1	29
35	Rotary Ultrasonic Machining of Potassium Dihydrogen Phosphate (KDP) crystal: an experimental investigation. International Journal of Mechatronics and Manufacturing Systems, 2009, 2, 414.	0.1	8
36	Grinding of silicon wafers: A review from historical perspectives. International Journal of Machine Tools and Manufacture, 2008, 48, 1297-1307.	13.4	140

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37	Simultaneous double side grinding of silicon wafers: a mathematical study on grinding marks. International Journal of Abrasive Technology, 2008, 1, 287.	0.2	4
38	Simultaneous double side grinding of silicon wafers: a mathematical model for the wafer shape. International Journal of Nanomanufacturing, 2008, 2, 556.	0.3	2
39	Soft-pad grinding of 300 mm wire-sawn silicon wafers: finite element analysis with designed experiments. International Journal of Manufacturing Technology and Management, 2008, 13, 169.	0.1	0
40	Rotary ultrasonic machining of titanium alloy (Ti-6Al-4V): effects of tool variables. International Journal of Precision Technology, 2007, 1, 85.	0.2	37
41	Rotary ultrasonic machining of silicon carbide: designed experiments. International Journal of Manufacturing Technology and Management, 2007, 12, 284.	0.1	42
42	Investigations of silicon wafer grinding using finite element analysis. International Journal of Computer Applications in Technology, 2007, 29, 102.	0.5	0
43	Non-destructive evaluation methods for subsurface damage in silicon wafers: a literature review. International Journal of Machining and Machinability of Materials, 2007, 2, 125.	0.1	14
44	ELID grinding of silicon wafers: A literature review. International Journal of Machine Tools and Manufacture, 2007, 47, 529-536.	13.4	42
45	Grinding wheels for manufacturing of silicon wafers: A literature review. International Journal of Machine Tools and Manufacture, 2007, 47, 1-13.	13.4	86
46	Subsurface damage measurement in silicon wafers with cross-polarisation confocal microscopy. International Journal of Nanomanufacturing, 2006, 1, 272.	0.3	9
47	Simultaneous double side grinding of silicon wafers: a literature review. International Journal of Machine Tools and Manufacture, 2006, 46, 1449-1458.	13.4	36
48	A grinding-based manufacturing method for silicon wafers: generation mechanisms of central dimples on ground wafers. International Journal of Machine Tools and Manufacture, 2006, 46, 397-403.	13.4	23
49	Edge-chipping reduction in rotary ultrasonic machining of ceramics: Finite element analysis and experimental verification. International Journal of Machine Tools and Manufacture, 2006, 46, 1469-1477.	13.4	89
50	Development of an innovative coolant system for rotary ultrasonic machining. International Journal of Manufacturing Technology and Management, 2005, 7, 318.	0.1	11
51	Rotary ultrasonic machining of ceramics: design of experiments. International Journal of Manufacturing Technology and Management, 2005, 7, 192.	0.1	55
52	Fine grinding of silicon wafers: effects of chuck shape on grinding marks. International Journal of Machine Tools and Manufacture, 2005, 45, 673-686.	13.4	26
53	A grinding-based manufacturing method for silicon wafers: an experimental investigation. International Journal of Machine Tools and Manufacture, 2005, 45, 1140-1151.	13.4	40
54	Fine grinding of silicon wafers: machine configurations for spindle angle adjustments. International Journal of Machine Tools and Manufacture, 2005, 45, 51-61.	13.4	26

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55	Experimental observation of tool wear in rotary ultrasonic machining of advanced ceramics. International Journal of Machine Tools and Manufacture, 2005, 45, 1468-1473.	13.4	102
56	Rotary ultrasonic machining of ceramic matrix composites: feasibility study and designed experiments. International Journal of Machine Tools and Manufacture, 2005, 45, 1402-1411.	13.4	256
57	Fine grinding of silicon wafers: a mathematical model for the wafer shape. International Journal of Machine Tools and Manufacture, 2004, 44, 707-716.	13.4	36
58	Waviness removal in grinding of wire-sawn silicon wafers: 3D finite element analysis with designed experiments. International Journal of Machine Tools and Manufacture, 2004, 44, 11-19.	13.4	21
59	An experimental investigation into soft-pad grinding of wire-sawn silicon wafers. International Journal of Machine Tools and Manufacture, 2004, 44, 299-306.	13.4	27
60	Finite element analysis for grinding of wire-sawn silicon wafers: a designed experiment. International Journal of Machine Tools and Manufacture, 2003, 43, 7-16.	13.4	40
61	Fine grinding of silicon wafers: a mathematical model for the chuck shape. International Journal of Machine Tools and Manufacture, 2003, 43, 739-746.	13.4	28
62	Fine grinding of silicon wafers: a mathematical model for grinding marks. International Journal of Machine Tools and Manufacture, 2003, 43, 1595-1602.	13.4	36
63	Finite element analysis for grinding and lapping of wire-sawn silicon wafers. Journal of Materials Processing Technology, 2002, 129, 2-9.	6.3	36
64	Modeling of material removal rate in rotary ultrasonic machining: designed experiments. Journal of Materials Processing Technology, 2002, 129, 339-344.	6.3	94
65	A study on surface grinding of 300 mm silicon wafers. International Journal of Machine Tools and Manufacture, 2002, 42, 385-393.	13.4	59
66	Fine grinding of silicon wafers: designed experiments. International Journal of Machine Tools and Manufacture, 2002, 42, 395-404.	13.4	73
67	Fine grinding of silicon wafers. International Journal of Machine Tools and Manufacture, 2001, 41, 659-672.	13.4	109
68	Grinding induced subsurface cracks in silicon wafers. International Journal of Machine Tools and Manufacture, 1999, 39, 1103-1116.	13.4	149
69	An experimental investigation of rotary ultrasonic face milling. International Journal of Machine Tools and Manufacture, 1999, 39, 1327-1344.	13.4	91
70	Modeling of ductile-mode material removal in rotary ultrasonic machining. International Journal of Machine Tools and Manufacture, 1998, 38, 1399-1418.	13.4	119
71	Plastic flow in rotary ultrasonic machining of ceramics. Journal of Materials Processing Technology, 1995, 48, 771-777.	6.3	92
72	Rotary ultrasonic machining for face milling of ceramics. International Journal of Machine Tools and Manufacture, 1995, 35, 1033-1046.	13.4	121